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(74) Agent: **BEALL, Thomas, R.**; Corning Incorporated, SP
TI 3 1, Corning, NY 14831 (US).

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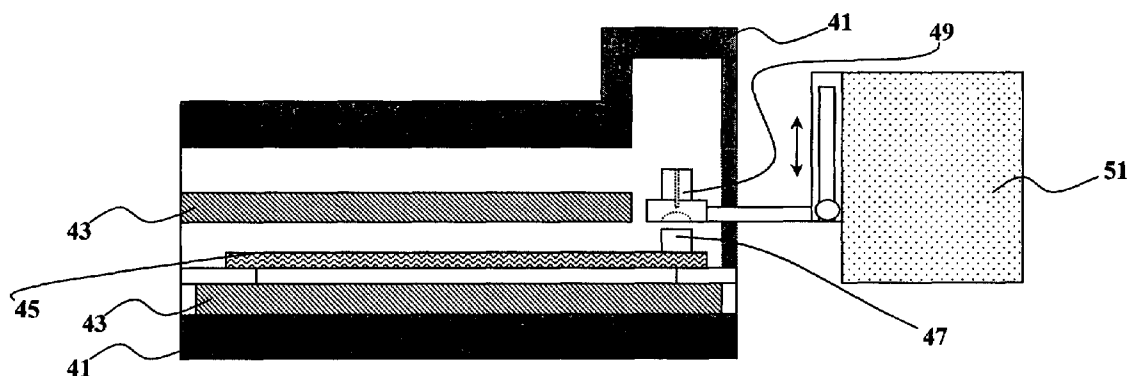
(71) Applicant: **CORNING INCORPORATED** [US/US]; 1
Riverfront Plaza, Corning, NY 14831 (US).

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(72) Inventors: **COOPER, Timothy, J.**; 3433 County Route
2, Addison, NY 14801 (US). **SHAH, Kashyap, H.**; 114
FieldView Drive, Painted Post, NY 14870 (US).

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(54) Title: SEALING LIGHTING DEVICE COMPONENT ASSEMBLY WITH SOLDER GLASS PREFORM BY USING INDUCTION HEATING



(57) Abstract: Disclosed is a process for sealing component assembly to an electrical lighting device using induction heating. The assembly comprises the component, such as an electrode lead wire, and a solder glass preform. The process is useful, for example, in hermetically sealing and affixing lamp components, such as electrical lead wires and exhaust tubulation, to a low-pressure fluorescent discharge lamp envelope having phosphor coating already applied thereto. The present invention is particularly suitable for lamp envelopes made of borosilicate glass having a CTE from 0 to 300°C in the range of 30-45x10⁻⁷ °C⁻¹.



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